



# PSMN6R9-100YSF

NextPower 100 V, 7 mΩ N-channel MOSFET in LFPACK56 package

8 December 2017

Product data sheet

## 1. General description

NextPower 100 V standard level gate drive MOSFET. Qualified to 175 °C and recommended for industrial & consumer applications.

## 2. Features and benefits

- Low  $Q_{rr}$  for higher efficiency and lower spiking
- Qualified to 175 °C
- Low  $Q_G \times R_{DSon}$  FOM for high efficiency switching applications
- Strong avalanche energy rating ( $E_{as}$ )
- Avalanche rated and 100% tested
- Ha-free and RoHS compliant LFPACK56 package
- Wave-solderable LFPACK56 package

## 3. Applications

- Synchronous rectifier in AC-DC and DC-DC
- BLDC motor control
- USB-PD and mobile fast-charge adapters
- LED lighting
- Full-bridge and half-bridge applications
- Flyback and resonant topologies

## 4. Quick reference data

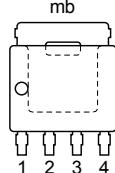
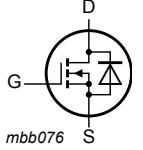
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$25 \text{ }^\circ\text{C} \leq T_j \leq 175 \text{ }^\circ\text{C}$	-	-	100	V
$I_D$	drain current	$V_{GS} = 10 \text{ V}; T_{mb} = 25 \text{ }^\circ\text{C}$ ; <a href="#">Fig. 2</a>	-	-	90	A
$P_{tot}$	total power dissipation	$T_{mb} = 25 \text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a>	-	-	238	W
<b>Static characteristics</b>						
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>	-	5.6	7	mΩ
<b>Dynamic characteristics</b>						
$Q_{GD}$	gate-drain charge	$I_D = 25 \text{ A}; V_{DS} = 50 \text{ V}; V_{GS} = 10 \text{ V}$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>	-	10.3	-	nC
<b>Source-drain diode</b>						
$Q_r$	recovered charge	$I_S = 25 \text{ A}; dI_S/dt = -100 \text{ A}/\mu\text{s}; V_{GS} = 0 \text{ V}; V_{DS} = 50 \text{ V}$ ; <a href="#">Fig. 16</a>	-	52.4	-	nC

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## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain	 <b>LFPAK56; Power-SO8 (SOT669)</b>	

## 6. Ordering information

Table 3. Ordering information

Type number	Package			Version
	Name	Description		
PSMN6R9-100YSF	LFPAK56; Power-SO8	Plastic single-ended surface-mounted package (LFPAK56; Power-SO8); 4 leads		SOT669

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PSMN6R9-100YSF	6F9S10

## 8. Limiting values

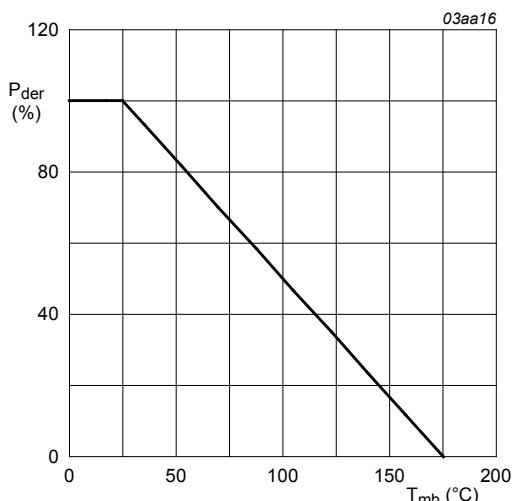
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	$25^{\circ}\text{C} \leq T_j \leq 175^{\circ}\text{C}$		-	100	V
$V_{DGR}$	drain-gate voltage	$25^{\circ}\text{C} \leq T_j \leq 175^{\circ}\text{C}; R_{GS} = 20\text{ k}\Omega$		-	100	V
$V_{GS}$	gate-source voltage			-20	20	V
$P_{\text{tot}}$	total power dissipation	$T_{mb} = 25^{\circ}\text{C}$ ; <a href="#">Fig. 1</a>		-	238	W
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{mb} = 25^{\circ}\text{C}$ ; <a href="#">Fig. 2</a>		-	90	A
		$V_{GS} = 10\text{ V}; T_{mb} = 100^{\circ}\text{C}$ ; <a href="#">Fig. 2</a>		-	88	A
$I_{DM}$	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; $T_{mb} = 25^{\circ}\text{C}$ ; <a href="#">Fig. 3</a>		-	360	A
$T_{\text{stg}}$	storage temperature			-55	175	°C
$T_j$	junction temperature			-55	175	°C
$T_{\text{std(M)}}$	peak soldering temperature			-	260	°C

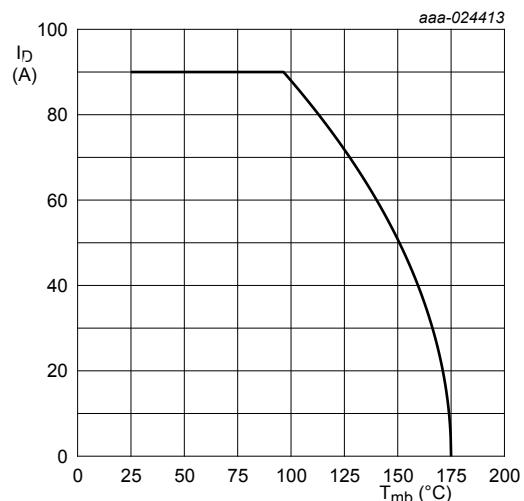
Symbol	Parameter	Conditions		Min	Max	Unit
<b>Source-drain diode</b>						
I <sub>S</sub>	source current	T <sub>mb</sub> = 25 °C		-	90	A
I <sub>SM</sub>	peak source current	pulsed; t <sub>p</sub> ≤ 10 µs; T <sub>mb</sub> = 25 °C		-	360	A
<b>Avalanche ruggedness</b>						
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	I <sub>D</sub> = 36 A; V <sub>sup</sub> ≤ 100 V; R <sub>GS</sub> = 50 Ω; V <sub>GS</sub> = 10 V; T <sub>j(init)</sub> = 25 °C; <a href="#">Fig. 4</a> ; Unclamped	[1]	-	321	mJ
I <sub>AS</sub>	non-repetitive avalanche current	V <sub>sup</sub> ≤ 100 V; V <sub>GS</sub> = 10 V; T <sub>j(init)</sub> = 25 °C; R <sub>GS</sub> = 50 Ω	[1]	-	36	A

[1] Protected by 100% test

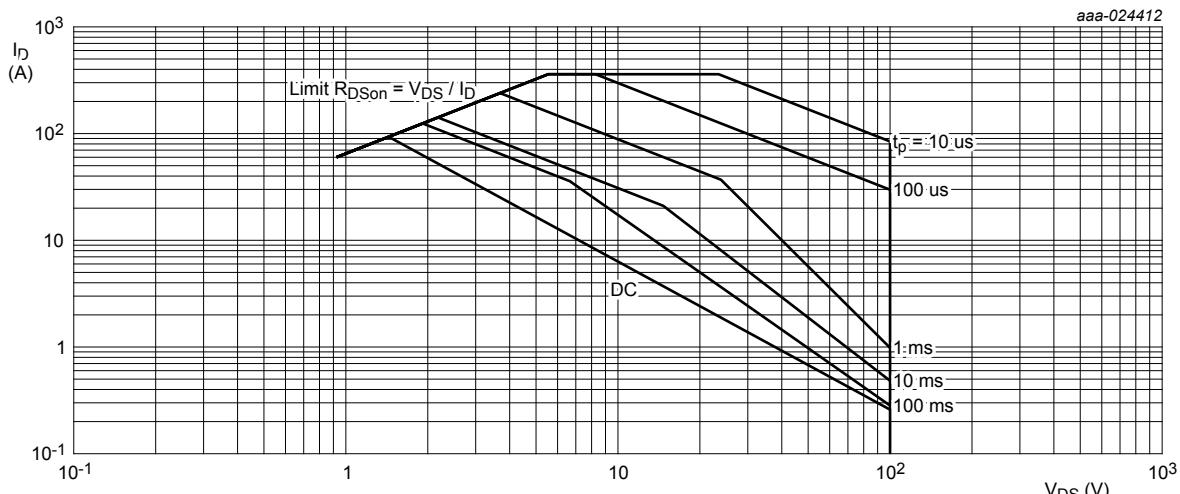


$$P_{der} = \frac{P_{tot}}{P_{tot}(25^\circ\text{C})} \times 100 \%$$

**Fig. 1. Normalized total power dissipation as a function of mounting base temperature**

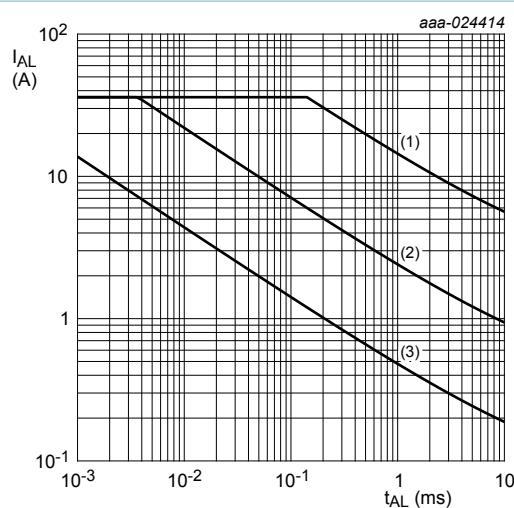


**Fig. 2. Continuous drain current as a function of mounting base temperature**



T<sub>mb</sub> = 25 °C; I<sub>DM</sub> is a single pulse

**Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage**



(1)  $T_j$  (init) = 25 °C; (2)  $T_j$  (init) = 150 °C; (3) Repetitive Avalanche

Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>	-	0.56	0.63	K/W

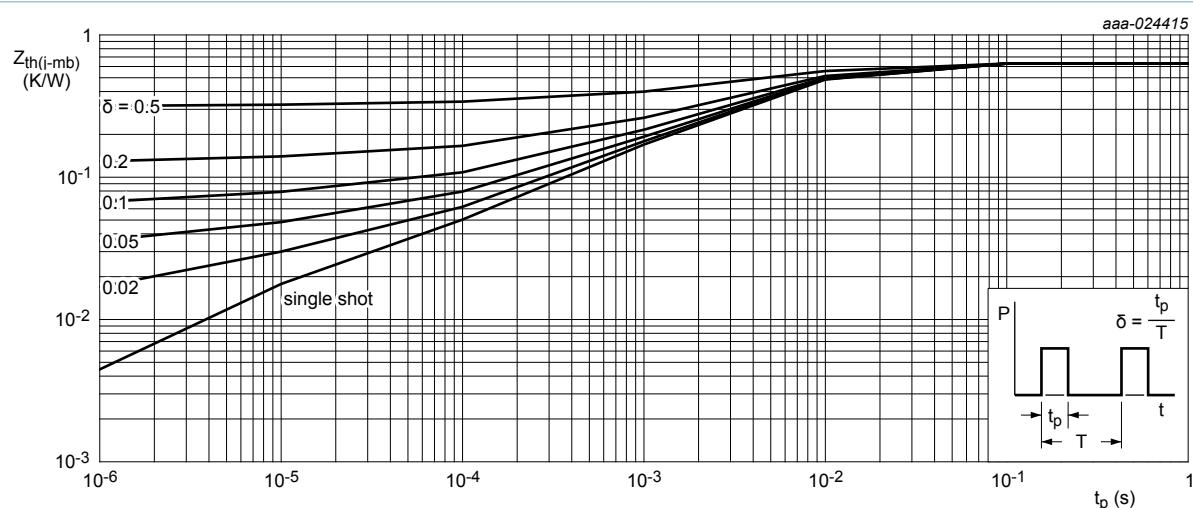


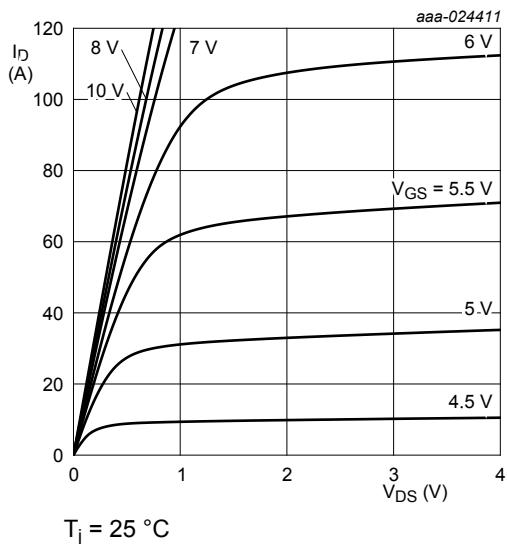
Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

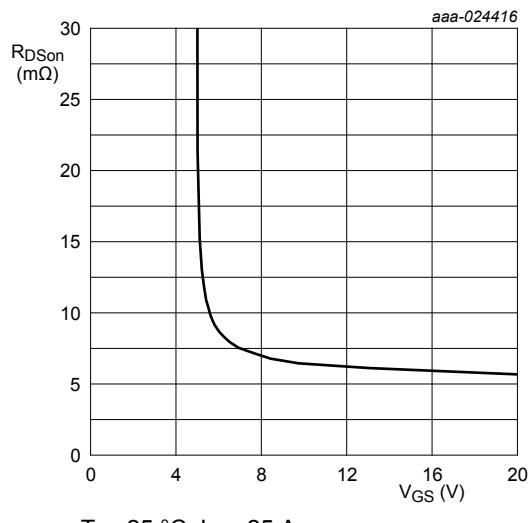
**Table 7. Characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25^\circ C$		100	-	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55^\circ C$		90	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 mA; V_{DS}=V_{GS}; T_j = -55^\circ C$		-	3.7	-	V
		$I_D = 1 mA; V_{DS}=V_{GS}; T_j = 175^\circ C$		-	2	-	V
		$I_D = 1 mA; V_{DS}=V_{GS}; T_j = 25^\circ C$ ; <a href="#">Fig. 9</a>		2	3.3	4	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	$25^\circ C \leq T_j \leq 175^\circ C$		-	-8.4	-	mV/K
$I_{DSS}$	drain leakage current	$V_{DS} = 100 V; V_{GS} = 0 V; T_j = 25^\circ C$		-	0.02	5	$\mu A$
		$V_{DS} = 100 V; V_{GS} = 0 V; T_j = 125^\circ C$		-	-	100	$\mu A$
$I_{GSS}$	gate leakage current	$V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	5	100	nA
		$V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	5	100	nA
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10 V; I_D = 25 A; T_j = 25^\circ C$ ; <a href="#">Fig. 10</a>		-	5.6	7	$m\Omega$
		$V_{GS} = 7 V; I_D = 25 A; T_j = 25^\circ C$ ; <a href="#">Fig. 10</a>		-	6.6	10.2	$m\Omega$
		$V_{GS} = 10 V; I_D = 25 A; T_j = 100^\circ C$ ; <a href="#">Fig. 11</a>		-	8.9	10.9	$m\Omega$
		$V_{GS} = 10 V; I_D = 25 A; T_j = 175^\circ C$ ; <a href="#">Fig. 11</a>		-	12.5	15.4	$m\Omega$
$R_G$	gate resistance	$f = 1 MHz$		-	0.9	-	$\Omega$
<b>Dynamic characteristics</b>							
$Q_{G(tot)}$	total gate charge	$I_D = 25 A; V_{DS} = 50 V; V_{GS} = 10 V$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>		-	50.3	-	nC
		$I_D = 0 A; V_{DS} = 0 V; V_{GS} = 10 V$		-	20.9	-	nC
$Q_{GS}$	gate-source charge	$I_D = 25 A; V_{DS} = 50 V; V_{GS} = 10 V$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>		-	17.1	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge			-	9.9	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge			-	7.2	-	nC
$Q_{GD}$	gate-drain charge			-	10.3	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 25 A; V_{DS} = 50 V$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>		-	5.1	-	V
$C_{iss}$	input capacitance	$V_{DS} = 50 V; V_{GS} = 0 V; f = 1 MHz$		-	3570	-	pF
$C_{oss}$	output capacitance	$V_{DS} = 50 V; V_{GS} = 0 V; f = 1 MHz; T_j = 25^\circ C$ ; <a href="#">Fig. 14</a>		-	722	-	pF
$C_{rss}$	reverse transfer capacitance			-	19	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 50 V; R_L = 2 \Omega; V_{GS} = 10 V$		-	14.8	-	ns
$t_r$	rise time	$R_{G(ext)} = 5 \Omega; T_j = 25^\circ C$		-	14.2	-	ns

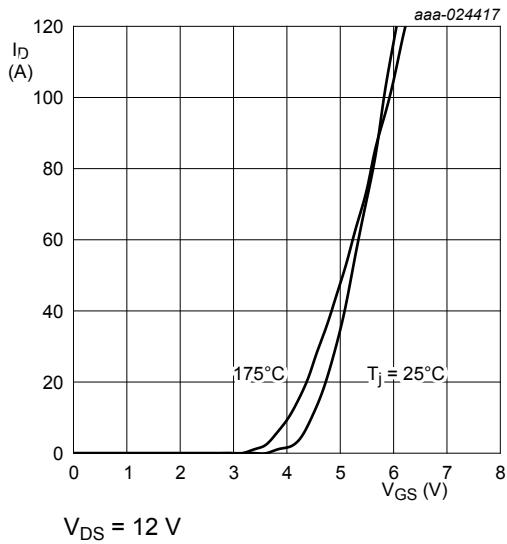
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$t_{d(\text{off})}$	turn-off delay time			-	27.6	-	ns
$t_f$	fall time			-	16	-	ns
<b>Source-drain diode</b>							
$V_{SD}$	source-drain voltage	$I_S = 25 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 15</a>		-	0.8	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 25 \text{ A}; dI_S/dt = -100 \text{ A}/\mu\text{s}; V_{GS} = 0 \text{ V}$ ; $V_{DS} = 50 \text{ V}$ ; <a href="#">Fig. 16</a>		-	45.4	-	ns
$Q_r$	recovered charge			-	52.4	-	nC



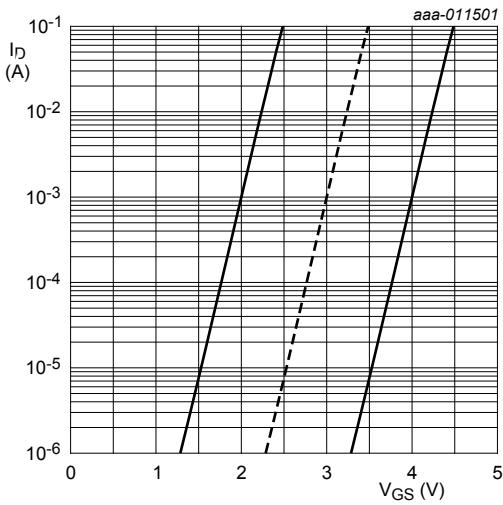
**Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values**



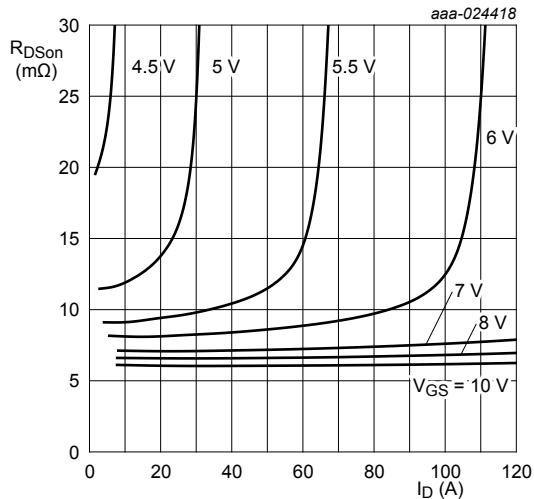
**Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values**



**Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values**

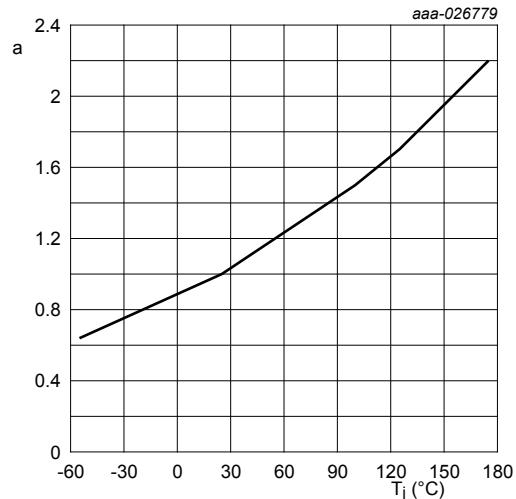


**Fig. 9. Sub-threshold drain current as a function of gate-source voltage**



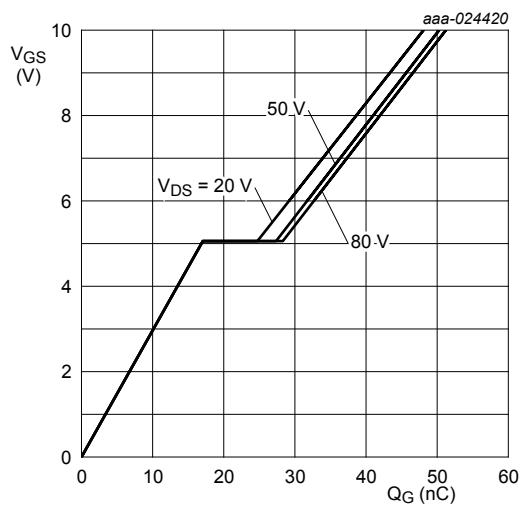
$T_j = 25^\circ\text{C}$

**Fig. 10. Drain-source on-state resistance as a function of drain current; typical values**



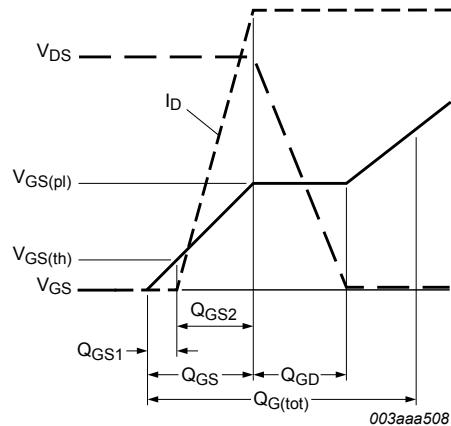
$$a = \frac{R_{DSon}}{R_{DSon} (25^\circ\text{C})}$$

**Fig. 11. Normalized drain-source on-state resistance factor as a function of junction temperature**

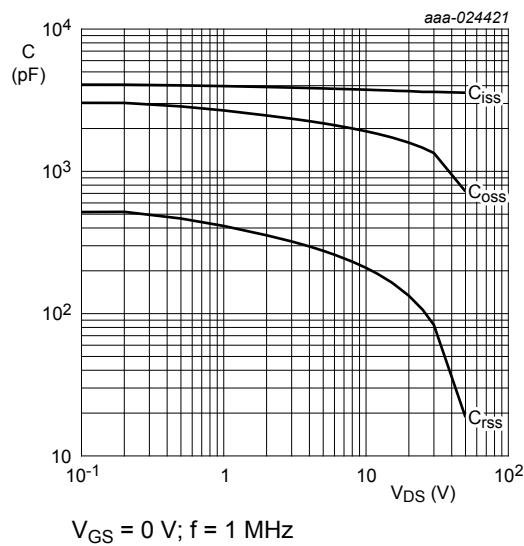


$T_j = 25^\circ\text{C}; I_D = 25\text{ A}$

**Fig. 12. Gate-source voltage as a function of gate charge; typical values**

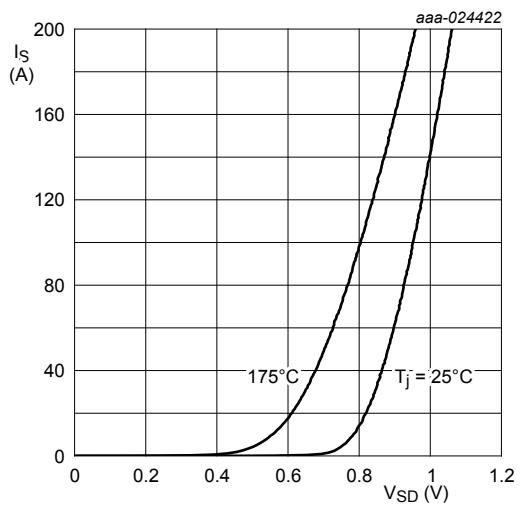


**Fig. 13. Gate charge waveform definitions**



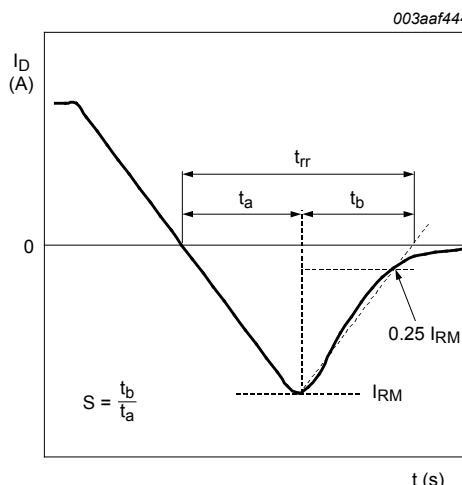
V<sub>GS</sub> = 0 V; f = 1 MHz

**Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**



V<sub>GS</sub> = 0 V

**Fig. 15. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values**



$$t_{rr} = t_a + t_b$$

**Fig. 16. Reverse recovery waveform definitions**

## 11. Package outline

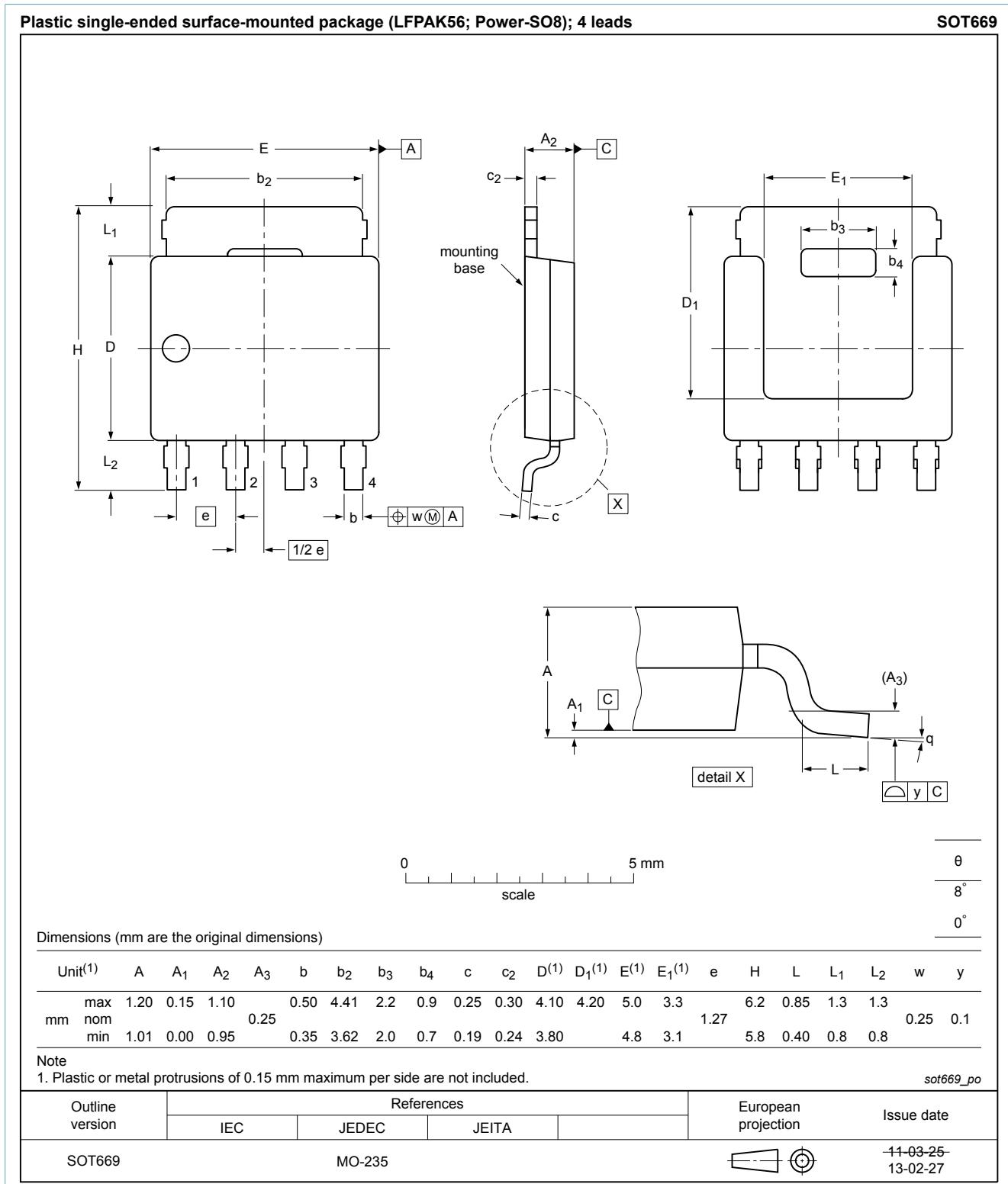
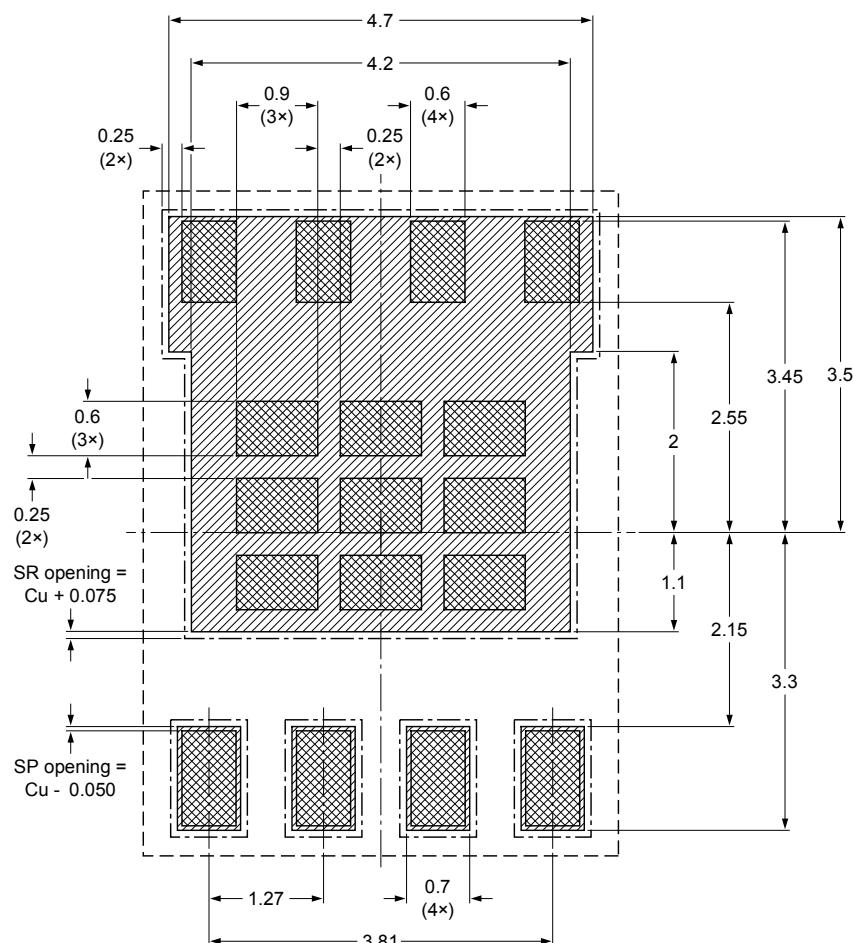


Fig. 17. Package outline LFPAK56; Power-SO8 (SOT669)

## 12. Soldering

## Footprint information for reflow soldering

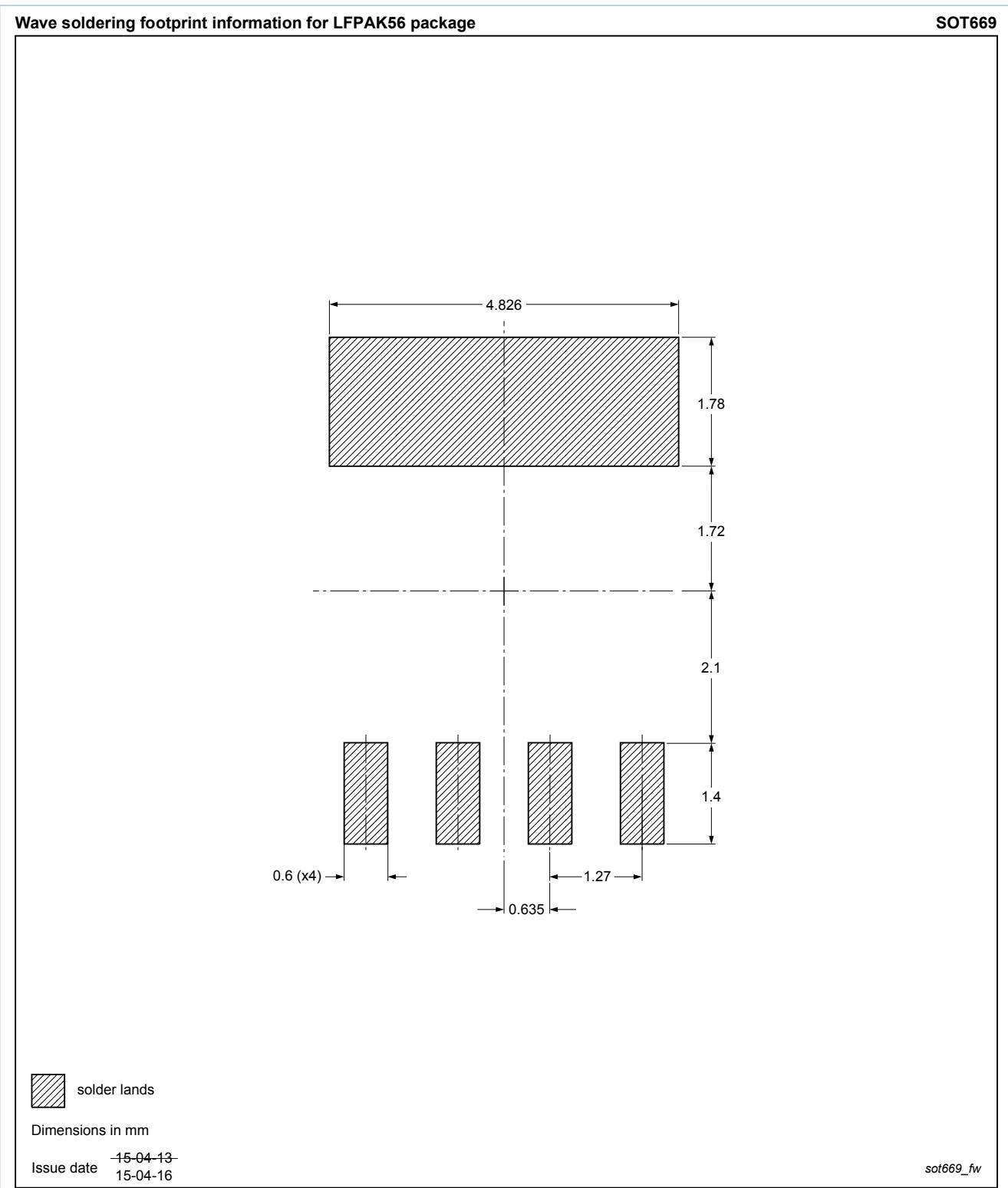
SOT669



Dimensions in mm

sot669 fr

Fig. 18. Reflow soldering footprint for LFPAK56: Power-SO8 (SOT669)



**Fig. 19. Wave soldering footprint for LFPAK56; Power-SO8 (SOT669)**

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### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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